505709416 10/07/2019

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1 Stylesheet Version v1.2 EPAS ID: PAT5756226

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
NABIL SVEN LOGHIN	09/13/2019
REKA INOVAN	09/13/2019

RECEIVING PARTY DATA

Name:	SONY SEMICONDUCTOR SOLUTIONS CORPORATION	
Street Address:	4-14-1 ASAHI-CHO	
Internal Address:	ATSUGI-SHI	
City:	KANAGAWA	
State/Country:	JAPAN	
Postal Code:	243-0014	

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	16603244

CORRESPONDENCE DATA

Fax Number:

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Email: XSENSUSPAT@XSENSUS.COM

Correspondent Name: XSENSUS, LLP

Address Line 1: 200 DAINGERFIELD ROAD

Address Line 2: SUITE 201

Address Line 4: ALEXANDRIA, VIRGINIA 22314

ATTORNEY DOCKET NUMBER:	13311US01	
NAME OF SUBMITTER:	TIERNEY FARRELL	
SIGNATURE:	/Tierney Farrell/	
DATE SIGNED:	10/07/2019	

Total Attachments: 2

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PATENT 505709416 REEL: 050634 FRAME: 0487

DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION USING AN APPLICATION DATA SHEET (37 CFR 1.76) AND ASSIGNMENT FOR SINGLE ASSIGNEE

Title of Invention	SHORTENED LDPC CODES WITH REPETITION OF CODE BITS FOR LOW THROUGHPUT NETWORKS		
As the below named inventor, I hereby declare that:			
This declaration	The attached application, or		
is directed to:	United States application or PCT international application number PCT/EP2018/059456 filed on 12 April 2018		
The above-identific	ed application was made or authorized to be made by me.		
I believe that I am t	the original inventor or an original joint inventor of a claimed invention in the application.		
	y Semiconductor Solutions Corporation		
(hereinafter referred to as "ASSIGNEE") having places of business at: 4-14-1 Asahi-cho, Alsugi-shi, Kanagawa, 243-0014 Japan, is desirous of acquiring the entire right, title and interest in and to said invention and in and to any Letters Patent that may be granted therefore in the United States and its territorial possessions and in any and all foreign countries;			
NOW, THEREFORE, for good, valuable, and adequate consideration, the receipt of which is hereby acknowledged, I, by these presents do sell, assign and transfer unto said ASSIGNEE, the full and exclusive right to the said invention in the United States and its territorial possessions and in all foreign countries (including the right to claim priority under the terms of the International Convention and other relevant International Treaties and Arrangements from the aforesaid application) and the entire right, title and interest in and to any and all Letters Patent which may be granted therefor in the United States and its territorial possessions and in any and all foreign countries and in and to any and all divisions, reissues, continuations, substitutions and renewals thereof.			
I hereby authorize and request the Patent Office Officials in the United States and its territorial possessions and any and all foreign countries to issue any and all of said Letters Patent, when granted, to said ASSIGNEE as the assignee of my entire right, title and interest in and to the same, for the sole use and behoof of said ASSIGNEE, its successors and assigns, to the full end of the term for which said Letters Patent may be granted, as fully and entirely as the same would have been held by me had this Assignment and sale not been made.			
Further, I agree that I will communicate to said ASSIGNEE or its representatives any facts known to me respecting said invention, and testify in any legal proceeding, sign all lawful papers, execute all divisional, continuation, substitute, renewal and reissue applications, execute all necessary assignment papers to cause any and all of said Letters Patent to be issued to said ASSIGNEE, make all rightful oaths, and, generally do everything possible to aid said ASSIGNEE, its successors and assigns, to obtain and enforce proper protection for said invention in the United States and its territorial possessions and in any and all foreign countries.			
Thereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.			
LEGAL NAME OF	.		
Inventor: Nabil Sve	n Loghin Date: 139.2025		
Signature: XXX			

XSENSUS LLP ATTORNEYS AT LAW 200 DAINGERFIELD ROAD, SUITE 201 Alexandria, VA 22314

> PATENT REEL: 050634 FRAME: 0488

DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION USING AN APPLICATION DATA SHEET (37 CFR 1.76) AND ASSIGNMENT FOR SINGLE ASSIGNEE

Title of Invention SHORTENED LDPC CODES WITH REPETITION OF CODE BITS FOR LOW THROUGHPUT NETWORKS		
As the below named inventor, I hereby declare that:		
This declaration The attached application, or		
is directed to: United States application or PCT international application number PCT/EP2018/059456 filed on 12 April 2018		
The above-identified application was made or authorized to be made by me.		
I believe that I am the original inventor or an original joint inventor of a claimed invention in the application.		
WHEREAS, Sony Semiconductor Solutions Corporation		
(hereinafter referred to as "ASSIGNEE") having places of business at: **14-1 Assisting Adaptive Assignment, 243-0014 Japan, is desirous of acquiring the entire right, title and interest in and to said invention and in and to any Letters Patent that may be granted therefore in the United States and its territorial possessions and in any and all foreign countries;		
NOW, THEREFORE, for good, valuable, and adequate consideration, the receipt of which is hereby acknowledged, I, by these presents do sell, assign and transfer unto said ASSIGNEE, the full and exclusive right to the said invention in the United States and its territorial possessions and in all foreign countries (including the right to claim priority under the terms of the International Convention and other relevant International Treaties and Arrangements from the aforesaid application) and the entire right, title and interest in and to any and all Letters Patent which may be granted therefor in the United States and its territorial possessions and in any and all foreign countries and in and to any and all divisions, reissues, continuations, substitutions and renewals thereof.		
I hereby authorize and request the Patent Office Officials in the United States and its territorial possessions and any and all foreign countries to issue any and all of said Letters Patent, when granted, to said ASSIGNEE as the assignee of my entire right, title and interest in and to the same, for the sole use and behoof of said ASSIGNEE, its successors and assigns, to the full end of the term for which said Letters Patent may be granted, as fully and entirely as the same would have been held by me had this Assignment and sale not been made.		
Further, I agree that I will communicate to said ASSIGNEE or its representatives any facts known to me respecting said invention, and testify in any legal proceeding, sign all lawful papers, execute all divisional, continuation, substitute, renewal and reissue applications, execute all necessary assignment papers to cause any and all of said Letters Patent to be issued to said ASSIGNEE, make all rightful oaths, and, generally do everything possible to aid said ASSIGNEE, its successors and assigns, to obtain and enforce proper protection for said invention in the United States and its territorial possessions and in any and all foreign countries.		
I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.		
LEGAL NAME OF INVENTOR		
Inventor: Reka Inovan Date: 13.09.2019		
Signature: Reka Indican		

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> PATENT REEL: 050634 FRAME: 0489

RECORDED: 10/07/2019